

LATEST NEWS *May 2017*



[ESCC QPL May 2017](#)

The ESCC QPL May was published with 1 extension for API Technologies - RF2M div. For more information please click [HERE](#)

[ESCC QML Issue 15 / May 2017](#)



The ESCC QML issue 15 was published May 9th 2017 includes:

- revised scope of Qualification for Microchip Atmel Technology Flows.
- extended qualification validity period: Vishay Sfernice Technology Flow
- added Process Capability Approvals for hermetic hybrid production lines of Airbus Defence and Space (France) and Safran-Sagem (France)
- other editorial changes affect bullet/ sub-paragraph numbers inside paragraphs as a result of the mentioned additions

C&K launches Micro-D Lightweight Backshell



"With the launch of our new product, C&K is the only supplier to offer a full range of flight and engineering models for Micro-D Lightweight Backshells" said Remi Antoine, product manager, Hi-Rel space and avionics at C&K. ESCC QPL Certified!! For more information please click [HERE](#)



NEW ESCC Specifications Published: RF Cable Assemblies

March 2017: A new ESCC Generic Specification for RF Cable Assemblies was published, ESCC [3408 issue 1](#), as well as ESCC [3408/001 issue 1](#); RF cable assembly, TNC, very high power, 50 ohms, semi-rigid and flexible cable, DC to 18 GHz

UPCOMING EVENTS



[8th Electronic Materials and Processes for Space \(EMPS\) Workshop](#)

This workshop will take place at ESA/ESTEC in Noordwijk 10 - 12 May 2017. The focus of the EMPS Workshop is set on high-reliability manufacturing of electronic assemblies intended to withstand assembly, storage and ground test conditions and the conditions imposed by launchers and the space flight environments.



[Materials and Processes Technology Board Stakeholder Day](#)

On the 16th of May 2017, the European Materials & Processes Technology Board (MPTB) is holding a one-day workshop on: REACH obsolescence risk and supply chain management for space programs



[IEEE Summer School 2017](#)

Nanoelectronic technologies and devices - From basic principle to highly reliable applications.

Organized by IRT Saint Exupéry - July 10 to 14, 2014 at LAAS-CNRS, Toulouse, France

RECENTLY PUBLISHED ESCC SPECIFICATIONS

Up-Issued ESCC Specifications published since 15th April 2017

Number	Title
REP 006	ESCC Qualified Manufacturers List REP006
22600	Requirements for the Evaluation of Standard Electronic Components for Space Application
23400	Microsection Examination Preparation and Evaluation of Capacitors Fixed Ceramic Leaded and Chips
5010	Generic Specification for Discrete Microwave Semiconductor Components
9000	Integrated Circuits: Monolithic And Multichip Microcircuits, Wire-Bonded, Hermetically Sealed And Flip-Chip Monolithic Mi ...

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